# Silicon Pixel R&D with EUDET Telescope in ESA

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https://confluence.slac.stanford.edu/display/Atlas/TestBeam

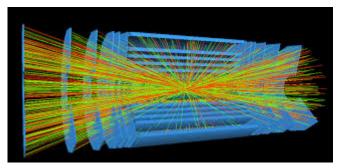
#### Scope

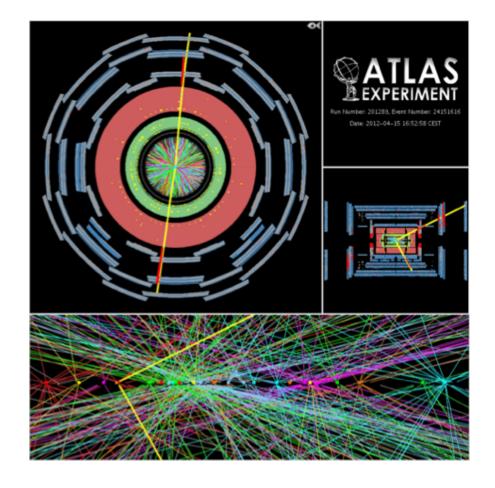
As part of the ATLAS collaboration at CERN, we are using the ESTB to study silicon detectors used for charged particle tracking:

- Precision momentum and direction measurements of tracks
- Tagging of short lived b quark decay secondary vertices coming from decays of Higgs and potential new particles

  IBL insertion 2014
- Test the performance of irradiated devices in order to validate and improve our models
  - 15 times more data (and radiation dose) to go on current detector until 2022
- 2. Study new devices that can be used in the upgrade of the ATLAS detector in 2023 for
  - 100 times more data than today
  - 10 times luminosity and radiation level
  - 100 times data rate





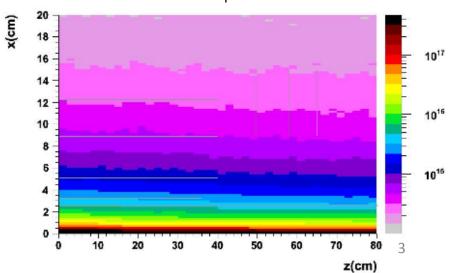


However, significant performance degradation is inevitable and we must be prepared with proper simulation!

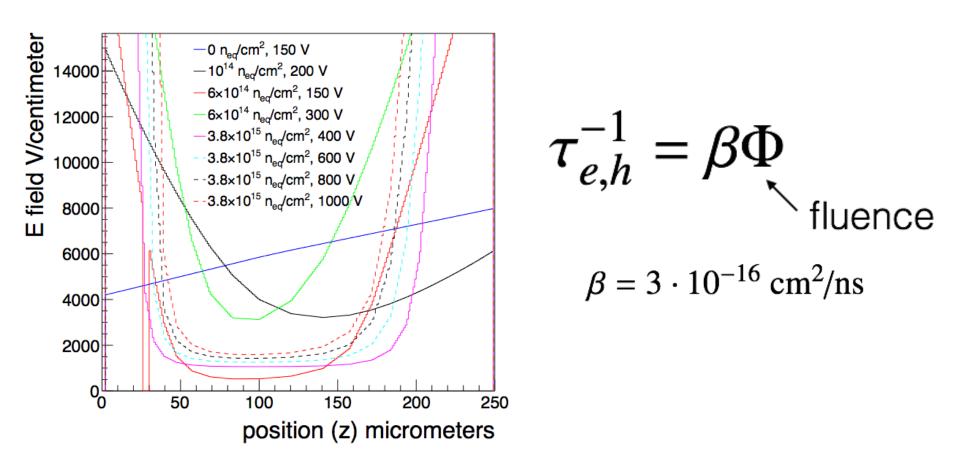
#### **Radiation Damage**

The use of radiation hard technology in the ATLAS inner detector is and will be crucial to maintain performance in Run II and beyond.

550/fb:  $^{\sim}$ 3e15  $n_{eq}$ /cm<sup>2</sup> for the IBL



## We have empirical models for rad. damage, but we need to validate them with TB data.



For example, radiation reduces the E field in the center of the pixel and causes charge trapping (signal loss)

#### ESTB Setup with EUDET Telescope

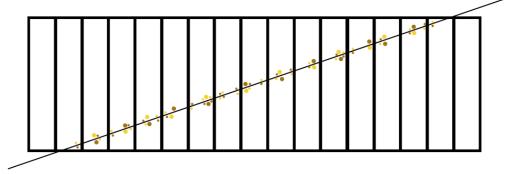
- 6 planes of precision CMOS EUDET pixel telescope (Caladium) from Carleton Univ.
- 18.5μm pixels with ~3μm spatial resolution
- ~ 2cm x 1cm beam aperture
- Integrated Device Under Test (DUT) readout and XY/rotation adjustment.



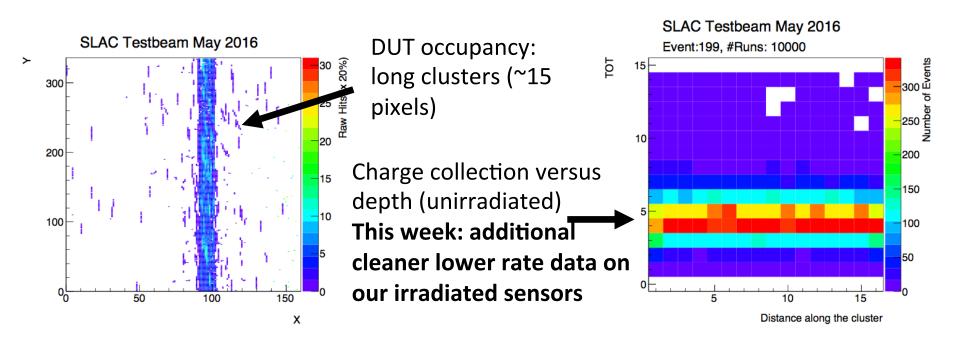
Allows selection of good tracks through whole telescope and less sensitive to beam debris contamination



DUT at high angles to probe charge collection as a function of depth in the sensor.



Critical for studying radiation damage effects and validating / improving our models.

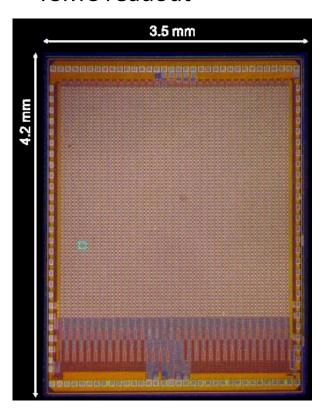


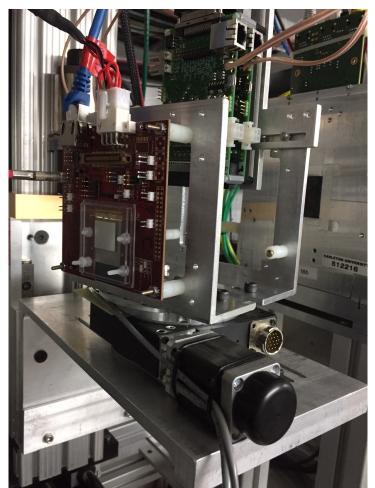
This will have a significant impact on ATLAS performance in the (near) future.

### **ATLAS Upgrade Devices**

#### RD53 FE65-P2 prototype

- 50μm x 50μm pixels
- Readout ASIC with 65nm TSMC readout





New prototype planar pixel sensors bump bonded by US vendor RTI to current readout chip.

Testing for bump and sensor uniformity.

### Beam Requirements

- Secondary electrons at the rate of a few electrons per beam crossing typically, and sometimes up to a few hundreds per crossing during setup tuning
- Prefers high energy beam >10 GeV to reduce multiple scattering but don't care about exact energy or moderate energy spread.
- Beam spot size preferably to cover large fraction of test device ~1x1cm – only worth fine tune for long data taking runs.
- Beam cleanness and energy spread not crucial we have EUDET telescope for offline quality selection. The key factor is hit density. Uniformity preferred.